BAS21HT1

Preferred Device

High Voltage Switching Diode

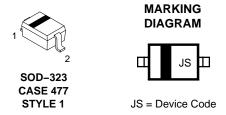
• Device Marking: JS



http://onsemi.com

HIGH VOLTAGE SWITCHING DIODE





MAXIMUM RATINGS

Symbol	Rating		Unit
V _R	Continuous Reverse Voltage	250	Vdc
V _{RRM}	Repetitive Peak Reverse Voltage	250	Vdc
lF	I _F Peak Forward Current		mAdc
I _{FM(surge)}	Peak Forward Surge Current	625	mAdc

THERMAL CHARACTERISTICS

Symbol	Characteristic		Unit
P _D	Total Device Dissipation FR–5 Board,* $T_A = 25^{\circ}C$		mW
	Derate above 25°C	1.57	mW/°C
$R_{\theta JA}$	Thermal Resistance Junction to Ambient		°C/W
T _J , T _{stg}	Junction and Storage Temperature Range	-55 to +150	°C

*FR-5 Minimum Pad

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

ORDERING INFORMATION

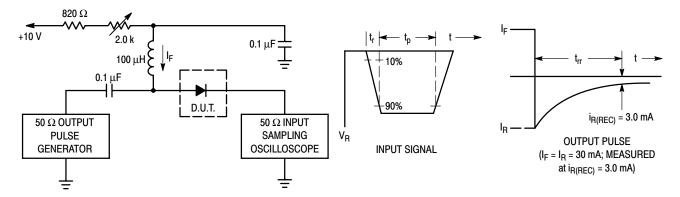
Device	Package	Shipping [†]
BAS21HT1	SOD-323	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Reverse Voltage Leakage Current $(V_R = 200 \text{ Vdc})$ $(V_R = 200 \text{ Vdc}, T_J = 150^{\circ}\text{C})$	I _R	_ _	0.1 100	μAdc
Reverse Breakdown Voltage (I _{BR} = 100 μAdc)	V _(BR)	250	-	Vdc
Forward Voltage (I _F = 100 mAdc) (I _F = 200 mAdc)	V _F	_ _	1000 1250	mV
Diode Capacitance (V _R = 0, f = 1.0 MHz)	C _D	-	5.0	pF
Reverse Recovery Time $(I_F = I_R = 30 \text{ mAdc}, R_L = 100 \Omega)$	t _{rr}	-	50	ns



Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (IF) of 30 mA.

- 2. Input pulse is adjusted so $I_{R(peak)}$ is equal to 30 mA.
- 3. $t_p \gg t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit

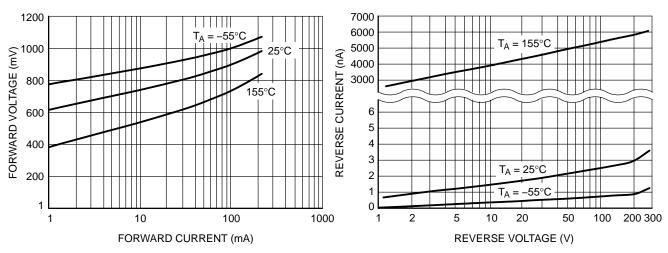


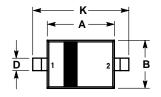
Figure 2. Forward Voltage

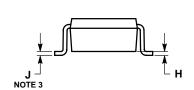
Figure 3. Reverse Leakage

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PACKAGE DIMENSIONS

SOD-323 PLASTIC PACKAGE CASE 477-02 ISSUE A





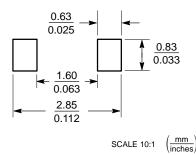


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	1.60	1.80	0.063	0.071
В	1.15	1.35	0.045	0.053
C	0.80	1.00	0.031	0.039
D	0.25	0.40	0.010	0.016
Е	0.15 REF		0.006 REF	
Н	0.00	0.10	0.000	0.004
J	0.089	0.177	0.0035	0.0070
K	2.30	2.70	0.091	0.106

STYLE 1: PIN 1. CATHODE 2. ANODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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